REVISIONS							
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED				
A	Change input to output voltage differential in 1.3, 1.4, $V_{\text{REE}'}$, $V_{\text{RLINE}'}$, I_{ADJ} , and delta I_{ADJ} conditions. Change I_{LIM} test limits for conditions ($V_{\text{IN}} - V_{\text{OUT}}$) = 2.5 V from 0.05 A to 0.075 A. Add case outline Y (T0-39).	92-08-19	M. A. Frye				
В	Changes in accordance with NOR 5962-R034-94.	92-12-23	M. A. Frye				
С	Add case outline Z. Technical and editorial changes throughout.	94-08-09	M. A. Frye				

THE FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

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REV				<u> </u>											
SHEET								<u> </u>							
REV															
SHEET															
REV STATUS	REV	С	С	С	С	С	С	С	С	С	С	С	С		
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12		
PMIC N/A PREPARED BY Joseph A Kerby			DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444												
STANDARDIZED MILITARY DRAWING	CHECKED BY Charles E Besc	CHECKED BY Charles E Besore													
THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE	APPROVED BY Michael A. Frye				REG	MICROCIRCUIT, LINEAR, POSITIVE REGULATOR, ADJUSTABLE, MONOLITHIC SILICON									
DEPARTMENT OF DEFENSE	DRAWING APPROVAL	DATE													
AMSC N/A	90-07-24	·····			SIZ	E	1	E CO			5	962-	899	81	
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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E080-94

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type Generic number Circuit function

O1 LT1086/OM186 Positive regulator, adjustable

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
x	See figure 1	2	TO-3 Can TO-257 Flange mounted,
U	See figure 1	3	with isolated tab
Y	See figure 1	3	T0-39 Can
ž	See figure 1	3	Z-tab

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein). Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and bulletin</u>. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits (Microcircuits) Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-I-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-I-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-I-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Case outline dimensions</u>. The case outline dimensions shall be as specified on figure 1.
- 3.2.3 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

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Test	Symbol	Conditions	1/	Group A	<u>L</u> i	mits	Unit
		-55°C ≤ T _A ≤ +125°C unless otherwise specific	ed	subgroups	Min	Max	
Reference voltage	VREF	I _{OUT} = 10 mA, (V _{IN} - V _{OUT}) = 3.0 V		1	1.238	1.262	٧
		1.5 V ≤ (V _{IN} - V _{OUT}) ≤ 15 V,	Cases X and Y	1,2,3	1.225	1.270	٧
		10 mA ≤ I _{OUT} ≤ I _{MAX}	Cases U and Z	1,2,3	1.220	1.270	
_ine regulation <u>2</u> /	V _{RLINE}	1.5 V ≤ (V _{IN} - V _{OUT}) ≤ 15 V, I _{OUT} = 10 mA		1,2,3		0.2	%
Load regulation 2/	VRLOAD	(V _{IN} - V _{OUT}) = 3.0 V,	 Cases X and Y	1	 	0.3	%
		10 mA ≤ I _{OUT} ≤ I _{MAX}	Cases U and Z	11		0.8	
			Cases X and Y	2,3		0.4	
			Cases	2,3	ļ ļ	1.0	
Dropout voltage	v _{DO}	I _{OUT} = I _{MAX} , delta V _{REF} = 1.0%		1,2,3	 	1.5	v
Thermal regulation		30 ms pulse, T _A = +25°C		1		0.04	%/W
Ripple rejection	ΔV _{IN} /	C _{ADJ} = 25 μF, f = 120 Hz,		4,5,6	60		dB
	ΔV _{OUT}	$C_{OUT} = 25 \mu\text{F} (\text{tantalum}),$					
		$\begin{vmatrix} 1_{OUT} & 1_{MAX'} \\ (V_{IN} - V_{OUT}) & = 3.0 \text{ V} \end{vmatrix}$		 	 	i 	
		1			1	1	1

See footnotes at end of table.

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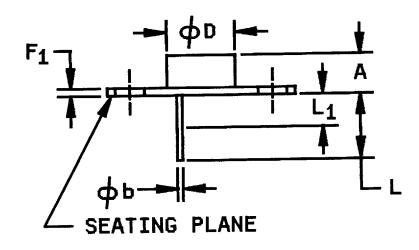
Test	Symbol	Conditions		Group A	<u>Li</u>	mits	Unit
		-55°C \le T_A \le +125°C unless otherwise specified	subgroup ed		Min	Max	
Adjust pin current change	ΔI _{ADJ}	10 mA \leq I _{OUT} \leq I _{MAX} , 1.5 V \leq (V _{IN} - V _{OUT}) \leq 15 V		1,2,3		5.0	µA
Minimum Load current	IMIN	(V _{IN} - V _{OUT}) = 25 V		1,2,3		10	mA
Current limit	ILIM	(V _{IN} - V _{OUT}) = 5.0 V	Case X Cases U and Z	1,2,3	1.5	2.8	_ ^
			Case Y		0.5	1.2	-
		(V _{IN} - V _{OUT}) = 25 V	Case X	1,2,3	0.05	1	_
			U and Z		0.075	 	-
			Case Y	<u> </u>	0.02	 	
Temperature stability 3/	ΔV _{OUT} /	-55°C ≤ T _J ≤ +125°C		1,2,3		1.5	%
Long term stability <u>3</u> /	ΔV _{OUT} /	T _A = +125°C, t = 1000 hrs		2		1.0	%

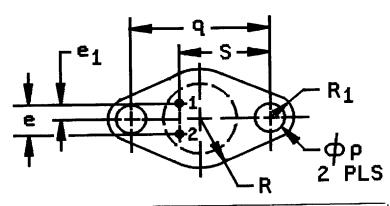
^{1/} For case outlines X, U, and Z, $\rm I_{MAX}$ = 1.0 A. For case outline Y, $\rm I_{MAX}$ = 0.5 A.

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Line and load regulation are measured at a constant junction temperature using a low duty cycle pulse technique. Although power dissipation is internally limited, regulation is guaranteed up to the maximum power dissipation of 15 W. Power dissipation is determined by the input/output differential voltage and the output current. Guaranteed maximum power dissipation will not be available over the full input/output voltage range.

 $[\]underline{3}/$ If not tested, shall be guaranteed to the limits specified in table I.



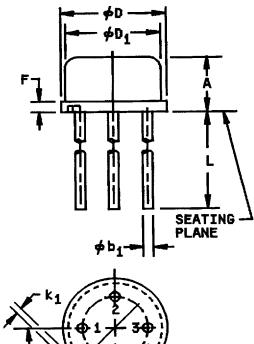


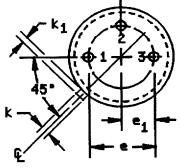
Symbol	Inches		<u>Millim</u>	eters
	Min	Max	Min_	Max
Α φb φ0 e e ₁	. 250 . 038 . 420 . 205 . 060	.450 .043 .875 .440 .225 .135	6.35 .97 10.67 5.21 1.52 7.92	11.43 1.09 22.23 11.18 5.72 2.43 12.70
L L1	.312 .151 1.177 .495 .131	.050 .161 1.197 .525 .188	3.84 29.90 12.57 3.33	1.27 4.09 30.40 13.34 4.78 17.15

NOTE: The US government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline.

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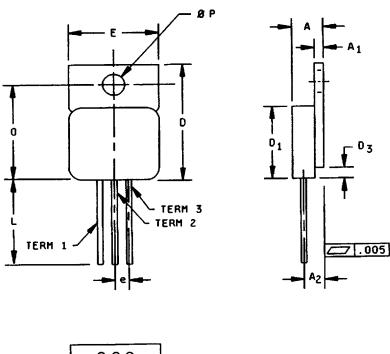
Symbol	Inch	Inches		ers
NOTE 1	Min	Max	_ Min	Max
Α	.165	.185	6.35	11.43
φb₁ i	.016	.019	.97	1.09
φ _D	.340	.370	İ	22.23
ϕ_{0_1}	.305	. 335	4.10	1.09
e'	.200 typ	NOTE 2	5.08 typ	NOTE 2
e,	.100 typ	NOTE 2	2.54 typ	NOTE 2
e ₁ k	.028	.038	7.92	12.70
k,	.026	.045	}	1.27
i L'i	.500	İ	7.92	

NOTES: 1. The US government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

2. Leads having a maximum diameter of .019 (0.48 mm) measured in gauging plane .054 ±.001 (1.37 ±0.03 mm) below the base plane of the product shall be within .007 (0.18 mm) of their true position relative to the maximum width tab.

FIGURE 1. <u>Case outline</u> - Continued.

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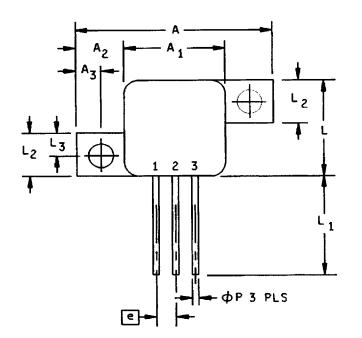
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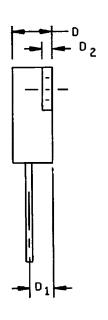
Symbol	Inches		Millim	eters
i i	Min	Max	Min	Max
A	.190	.200	4.83	5.08
A ₁	.035	.045	.89	1.14
	120 bsc		3.05 bsc	
$\phi_{b}^{A\dot{2}}$.025	.035	.64	.89
i Ď	. 645	.665	16.38	16.89
D ₁	. 410	. 430	10.41	10.92
	İ	.065	į	1.65
P3 e	.100 bs	sc	2.54	bsc
E	.410	. 422	10.41	10.72
L	.500	.750	12.70	19.05
i o	.527	.537	13.39	13.64
φ ρ	.140	150	3.56	3.81

NOTE: The US government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. <u>Case outline</u> - Continued.

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Symbol _	Inch	es	Millime	eters
	Min	Max	Min	Max
A	.910	.920	23.11	23.37
A ₁	.410	.420	10.41	10.67
A ₂	. 245	.255	6.22	6.48
1 AZ 1	.120	.130	3.05	3.30
φ _b	.120	.130	3.05	3.30
D	.135	. 220	4.70	5.59
D ₁	.115	.125	2.92	3.18
02	.035	.045	0.89	1.14
e^	,100 bs	S C	2.54	bsc
L	.410	. 420	10.41	10.67
أ لم أ	.500	.750	12.70	19.05
L2	.245	.255	6.22	6.48
L ₃	.120	.130	3.05	3.30
i obo i	.028	.032	0.71	0.81

NOTE: The US government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. <u>Case outline</u> - Continued.

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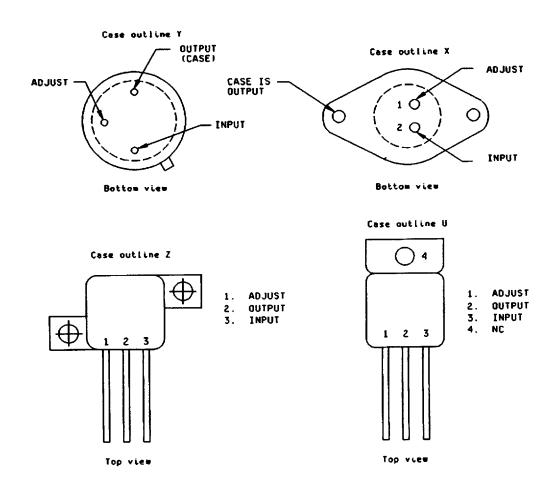


FIGURE 2. <u>Terminal connections</u>.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 4, 5, 6
Group A test requirements (method 5005)	1, 2, 3, 4, 5, 6
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

*PDA applies to subgroup 1.

- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

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4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7, 8A, 8B, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein).

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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